


MATERIAL DECLARATION SHEET



Material Number	CRM1206			
Product Line	High power chip resistors			
Compliance Date	7-27-2007			
RoHS Compliant	Yes (Lead Exemption)	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	8.5880	Aluminum oxide	1344-28-1	96	81.946	85.36
				Silicon dioxide	7631-86-9	4	3.414	
				Magnesium oxide	1309-48-4			
2	Top conductor	Silver	0.1620	Silver	7440-22-4	100	1.610	1.610
3	Bottom conductor	Silver	0.0543	Silver	7440-22-4	100	0.540	0.540
4	Resistor	Ruthenium Oxide	0.1087	Silver	7440-22-4	40	0.432	1.080
				Ruthenium dioxide	12036-10-1	20	0.216	
				Palladium	7440-05-3	15	0.162	
				Lead glass	7439-92-1	25	0.270	

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5	First encapsulating	Resin	0.1038	Bismuth trioxide	1304-76-3	50	0.516	1.032
				Resin	25036-25-3	30	0.31	
				Aluminum oxide	1344-28-1	10	0.103	
				Boron	7440-42-8	10	0.103	
6	Overcoat	Epoxy	0.2327	Epoxy	25036-25-3	100	2.313	2.313
7	Side conductor	Silver	0.2341	Silver	7440-22-4	85	1.978	2.327
				Epoxy	9003-36-5	15	0.349	
8	Plating (Middle)	Nickel	0.1985	Nickel	7440-02-0	100	1.973	1.973
9	Plating (Outer)	Tin	0.3573	Tin	7440-31-5	100	3.551	3.551
10	Marking	Epoxy	0.0215	Epoxy	25068-38-6	70	0.150	0.214
				Titanium dioxide	1317-80-2	30	0.064	
Total weight			10.0609					

This Document was updated on: 10/29/2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption – 7c-I Lead in glass of ..., electronic components.